

IMPEDANCE REQUIREMENTS +/- 10%			
LAYER	50 OHMS LINE WIDTH (MILS)	100 OHMS DIFFERENTIAL LINE WIDTH/SPACING (MILS)	90 OHMS DIFFERENTIAL LINE WIDTH/SPACING (MILS)
1	7.5	5/7	6/6
3	4.8		5.2/5.8
5	4.8		
10		4.5/7.25	
12	4.8	4.5/7.25	
14	7.5		

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- 10%. BOARD OUTLINE DIMENSIONS ARE FOR REFERENCE ONLY. SEE GERBER FILES FOR EXACT BOARD OUTLINE DIMENSIONS.
- THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT. RoHS TO BE MARKED ON THE FINISHED BOARD.
- ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .076 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- ANY DESCREPENCY BETWEEN FABRICATION PRINT AND THE ACTUAL FABRICATION DATA MUST BE REVIEWED AND APPROVED.

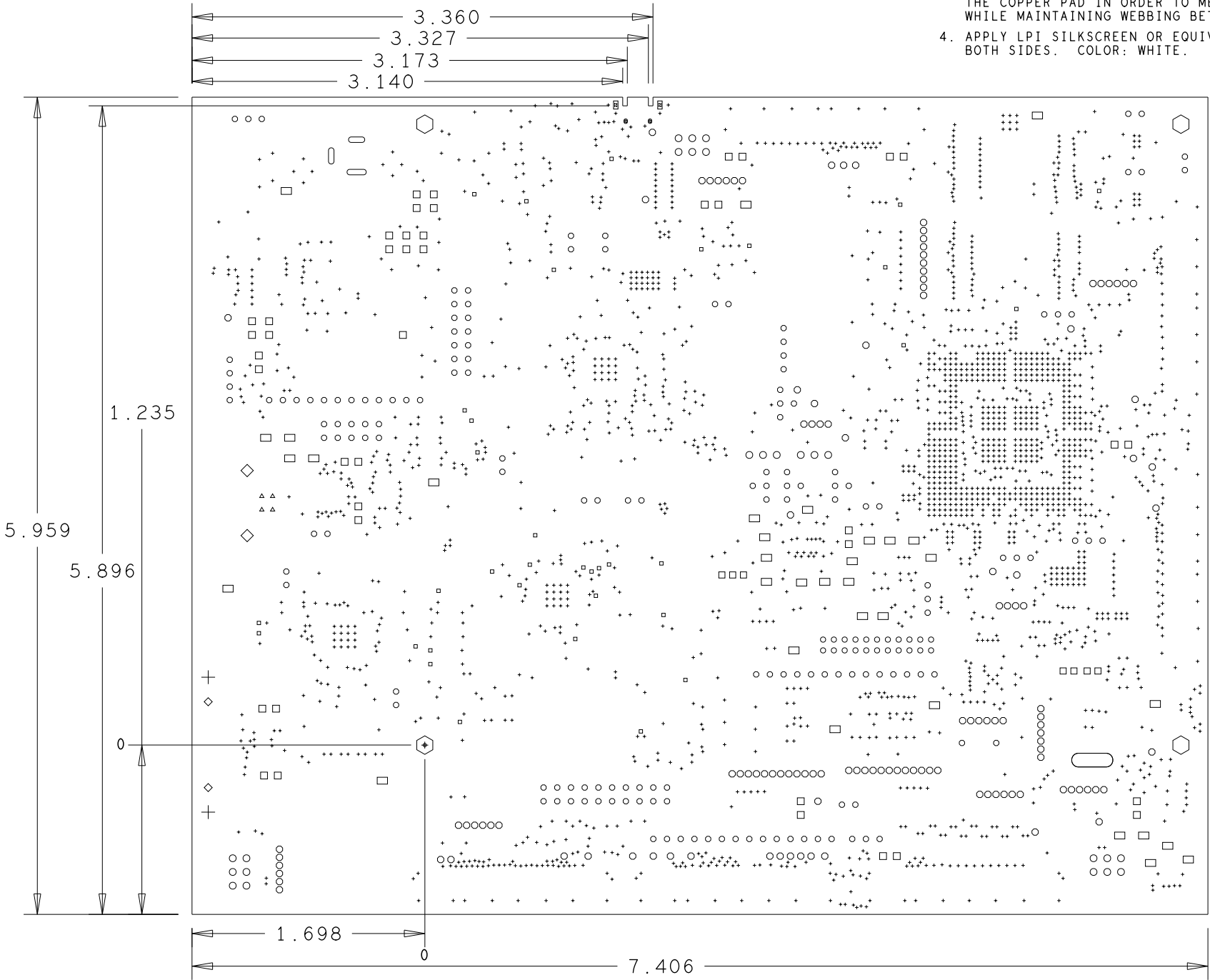
PROCESS NOTES:

- PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MICROINCHES THK MIN, GOLD 2-6 MICROINCHES THK.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- APPLY LPI OR LDI SOLDERMASK.  
COLOR: PURPLE  
CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.  
FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK BOTH SIDES. COLOR: WHITE.

LAYER STACKUP

LAYER	DEFINITION	PREPREG/CORE THICKNESS (MILS)	Cu WT.
	SILKSCREEN		
	SOLDERMASK		
1	SIGNAL		1/2 OZ
PREPREG			
2	GND PLANE		1 OZ
CORE			
3	SIGNAL		1/2 OZ
PREPREG			
4	GND PLANE		1 OZ
CORE			
5	SIGNAL		1/2 OZ
PREPREG			
6	GND PLANE		1 OZ
CORE			
7	SPLIT PLANE		1 OZ
PREPREG			
8	SPLIT PLANE		1 OZ
CORE			
9	GND PLANE		1 OZ
PREPREG			
10	SIGNAL		1/2 OZ
CORE			
11	GND PLANE		1 OZ
PREPREG			
12	SIGNAL		1/2 OZ
CORE			
13	GND PLANE		1 OZ
PREPREG			
14	SIGNAL		1/2 OZ
	SOLDERMASK		
	SILKSCREEN		

0.076 ± 10%



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	8.0	+0.0/-8.0	PLATED	2451
□	12.0	+0.0/-12.0	PLATED	35
○	28.0	+3.0/-3.0	PLATED	127
△	36.0	+3.0/-3.0	PLATED	4
◦	38.0	+3.0/-3.0	PLATED	22
◻	40.0	+3.0/-3.0	PLATED	41
◌	42.0	+3.0/-3.0	PLATED	156
◻	45.0	+3.0/-3.0	PLATED	7
◌	50.0	+3.0/-3.0	PLATED	24
◻	63.0	+3.0/-3.0	PLATED	34
◇	90.0	+3.0/-3.0	PLATED	2
+	126.0	+3.0/-3.0	PLATED	2
◇	59.0	+3.0/-3.0	NON-PLATED	2
⬡	135.0	+3.0/-3.0	NON-PLATED	4
•	33.5x25.6	+3.0/-3.0	PLATED	2
⊞	59.06x32.68	+3.0/-3.0	PLATED	2
⊖	118.11x40.0	+2.99/-2.99	PLATED	1
∅	118.11x40.0	+2.99/-2.99	PLATED	1
⊖	140.0x40.0	+2.99/-2.99	PLATED	1
⊖	300.0x100.0	+3.0/-3.0	NON-PLATED	1



TEXAS INSTRUMENTS			
BOARD NAME: DLPC7540EVM FORMATTER BOARD		DESCRIPTION: FAB DWG	
PROJECT #: DLP055		DATE: 16-APR 2021	REVISION: C